

MacDermid Alpha's Kester Brand to Exhibit at China International Optoelectronic Exposition

(Itasca, IL USA) – September 2, 2020 – The Kester brand of MacDermid Alpha Electronics Solutions, a world leader in the production of electronics soldering and bonding materials, will be represented by China Distributor, Shanghai Fairfield Electronic Technology Co., Ltd., at the China International Optoelectronic Exposition (CIOE) in Shenzhen, China from September 9-11.

Kester will be highlighting its tacky solder flux and solder paste portfolio. Kester [Tacky Solder Fluxes](#) (TSFs) are the industrial standard for Flip Chip and BGA Sphere Attach. With viscosities optimized for high speed application and holding of a chip or sphere in place prior to reflow, Kester TSFs enable wide process windows for our users. Known for their active soldering, Kester TSFs ensure good electrical connections on known good die and components. Featured products include TSF-6522RH, TSF-ULR18, and TSF-WS917.

Additionally, Kester will exhibit three of its leading solder pastes. [Kester NP560](#) is a no-clean, lead-free, halogen-free solder paste that has redefined the voiding standard for PCB assembly. This paste consistently delivers paste transfer efficiencies of 0.50 to 0.55 AR and is fully capable of printing and reflowing 01005 components, even in air, with minimal graping behavior. [Kester NP545](#) is a zero-halogen, lead-free, no-clean solder paste formula designed for consistency and repeatability, and [Kester NP505-HR](#) is a zero-halogen, lead-free, no-clean solder paste formula developed specifically for high reliability applications.

For more information on Kester's Tacky Solder Flux and Solder Paste solutions, please visit Kester in Hall: 8, Booth No:8E161 or visit the www.kester.com.

China International Optoelectronic Exposition (CIOE 2020)

Dates: September 9-11, 2020

Venue: Shenzhen World Exhibition & Convention Center

<http://www.cioe.cn/en/>